

ABSTRACTSUBSTRATE LOADING APPARATUS

5 *Sub p1* The present invention provides apparatus for loading a substrate (65) onto a processing surface (61) in a thin-film processing chamber (60). The apparatus includes a support (66) which cooperates with one or more corresponding apertures (62) in the processing surface so 10 as to be movable between an extended position in which the support can support a substrate (65) above the processing surface (61), and a retracted position in which the support is flush with or located below the processing surface (61). The support has a number of limbs (64) which extend 15 radially outwardly from a central hub, at an angle relative to the processing surface. The limbs contact the edges of different sized substrates in use so as to support the substrate in a support plane above the central hub and substantially parallel to the processing surface.